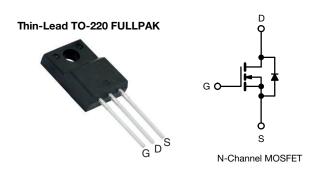
COMPLIANT

HALOGEN

FREE



E Series Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	8	50
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.38
Q _g max. (nC)	8	88
Q _{gs} (nC)	,	9
Q _{gd} (nC)	1	6
Configuration	Sir	ngle

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	Thin-lead TO-220 FULLPAK
Lead (Pb)-free and halogen-free	SiHA11N80E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unless otherwise	noted)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	800	V	
Gate-source voltage		V_{GS}	± 30	V	
Continuous drain current (T _{.J} = 150 °C) ^a	V_{GS} at 10 V $T_C = 25 ^{\circ}C$	L	12		
Continuous drain current (1) = 150 °C) "	V_{GS} at 10 V $T_C = 100 ^{\circ}C$	l _D	8	Α	
Pulsed drain current ^b		I _{DM}	32		
Linear derating factor			0.27	W/°C	
Single pulse avalanche energy c		E _{AS}	226	mJ	
Maximum power dissipation		P_{D}	34	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	T _J = 125 °C	70		V/ns	
Reverse diode dv/dt ^d		dv/dt	4.3	V/IIS	
Soldering recommendations (peak temperature) e	For 10 s		300	°C	
Mounting torque	M3 screw		0.6	Nm	

Notes

- a. Limited by maximum junction temperature
- b. Repetitive rating; pulse width limited by maximum junction temperature
- c. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 4.0 A
- d. $I_{SD} \le I_D$, di/dt = 100 A/µs, starting $T_J = 25$ °C
- e. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATIN	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	3.7	C/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	V _{GS} =	= 0 V, I _D = 250 μA	800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	1.1	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	- V _{GS} , I _D = 250 μA	2	-	4	٧
Only the second ball and		,	V _{GS} = ± 20 V	-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zove gets valtege dusin suggest		V _{DS} =	V _{DS} = 800 V, V _{GS} = 0 V		-	1	, . ^
Zero gate voltage drain current	I _{DSS}	V _{DS} = 640 V	', V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 5.5 A	-	0.38	0.44	Ω
Forward transconductance	9 _{fs}	V _{DS} :	= 30 V, I _D = 5.5 A	-	4.5	-	S
Dynamic							
Input capacitance	C _{iss}		V _{GS} = 0 V,		1670	-	
Output capacitance	C _{oss}	·	$V_{DS} = 100 V$	-	68	-	
Reverse transfer capacitance	C _{rss}		f = 1 MHz	-	9	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	43	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}			-	212	-	
Total gate charge	Q_g			-	44	88	
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$I_D = 5.5 \text{ A}, V_{DS} = 480 \text{ V}$	-	9	-	nC
Gate-drain charge	Q_{gd}			-	16	-	
Turn-on delay time	t _{d(on)}			-	18	36	
Rise time	t _r	$V_{DD} = 480 \text{ V}, I_D = 5.5 \text{ A},$		-	15	30	ns
Turn-off delay time	t _{d(off)}		$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		55	110	
Fall time	t _f	1		-	18	36	
Gate input resistance	R _g	f = 1 MHz, open drain		0.4	0.9	1.8	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	Is	MOSFET sym	MOSFET symbol		-	12	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	32	- A
Diode forward voltage	V_{SD}	T _J = 25 °C	C, I _S = 5.5 A, V _{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t _{rr}			-	345	690	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}$, $I_F = I_S = 5.5 \text{A}$, $\text{di/dt} = 100 \text{A/}\mu\text{s}$, $V_R = 25 \text{V}$		-	4.2	8.4	μC
Reverse recovery current	I _{RRM}			-	21	-	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

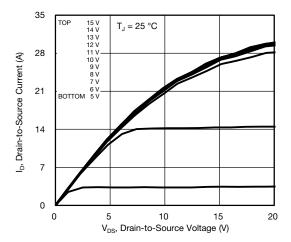


Fig. 1 - Typical Output Characteristics

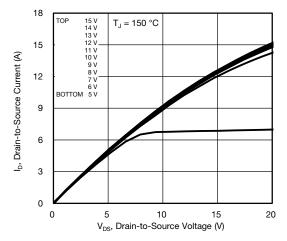


Fig. 2 - Typical Output Characteristics

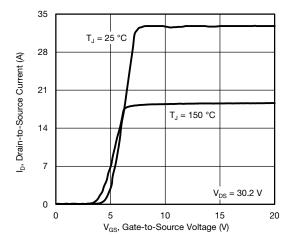


Fig. 3 - Typical Transfer Characteristics

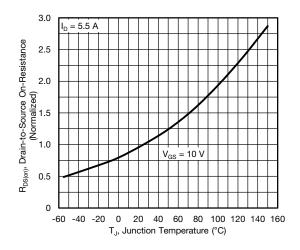


Fig. 4 - Normalized On-Resistance vs. Temperature

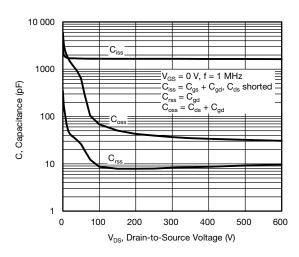


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

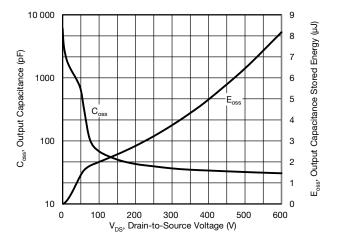


Fig. 6 - C_{oss} and $E_{oss}\, vs.\, V_{DS}$



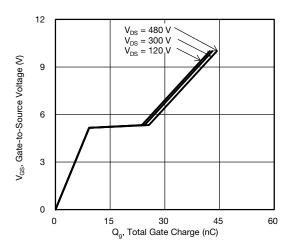


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

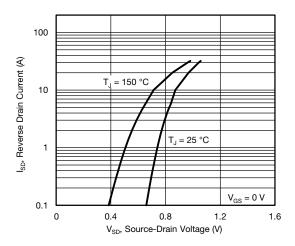


Fig. 8 - Typical Source-Drain Diode Forward Voltage

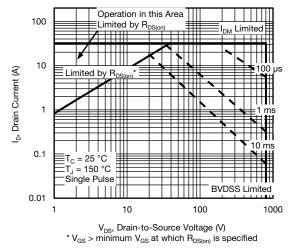


Fig. 9 - Maximum Safe Operating Area

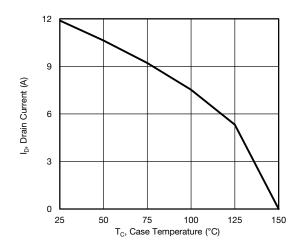


Fig. 10 - Maximum Drain Current vs. Case Temperature

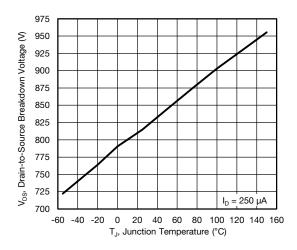


Fig. 11 - Temperature vs. Drain-to-Source Voltage



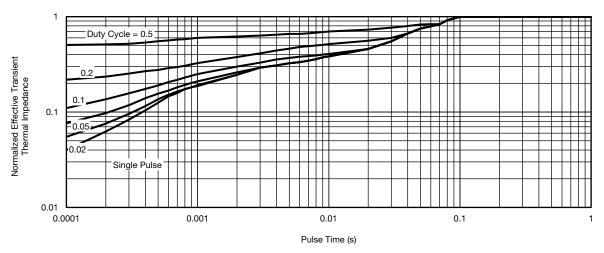


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

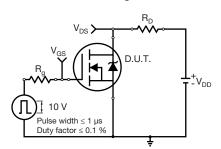


Fig. 13 - Switching Time Test Circuit

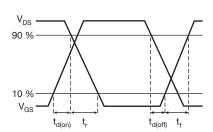


Fig. 14 - Switching Time Waveforms

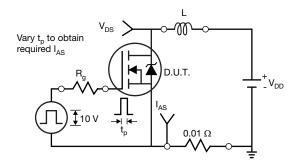


Fig. 15 - Unclamped Inductive Test Circuit

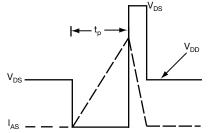


Fig. 16 - Unclamped Inductive Waveforms

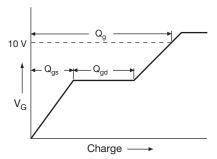


Fig. 17 - Basic Gate Charge Waveform

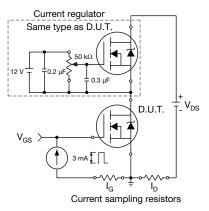
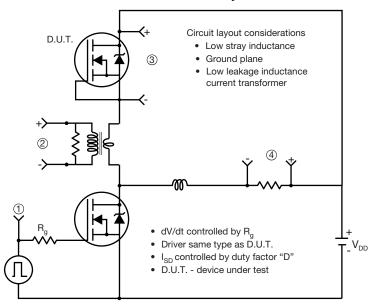


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



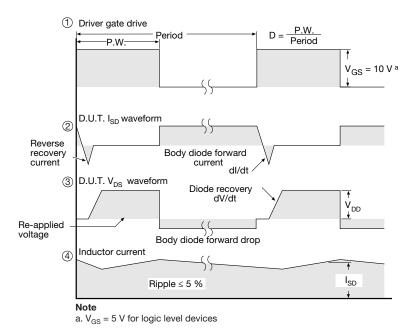


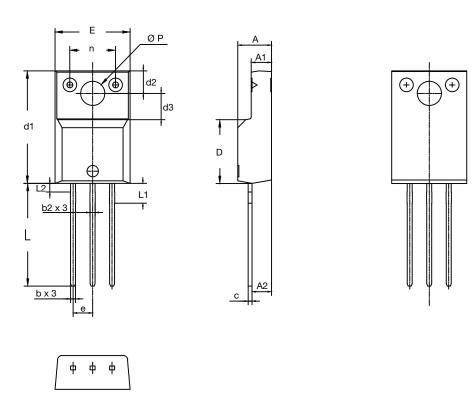
Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead



SYMBOL	MILLIN	METERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.50	2.70	0.098	0.106
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	-	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.40	3.60	0.134	0.142
Е	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	2.50	2.80	0.098	0.110
L2	-	1.20	-	0.047
n	6.05	6.15	0.238	0.242
ØP	3.00	3.40	0.118	0.134

Revision: 12-Sep-16 1 Document Number: 62649



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